Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)

Contact Info: Form/Declaration Type: ti.com/support
Distribute - RoHS and IEC 62474 DB

Created on: 06/08/2022

## Details for "TLC2272AMDG4"

### **Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TLC2272AMDG4	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	D   8	3.91x4.9x1.58	82.1

### \*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

## **Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

### Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire	*	•					
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000001	0.001235	12	0.000001	
Precious Metals	Gold	7440-57-5	0.080964	99.99753	999975	0.09861	98
Precious Metals	Silver	7440-22-4	0.000001	0.001235	12	0.000001	
Sub-Total			0.080966	100	1000000	0.098612	98
Die Attach Adhesive				•			
Precious Metals	Silver	7440-22-4	0.184747	70.000076	700001	0.225012	225
Thermoplastics	Epoxy	85954-11-6	0.079177	29.999924	299999	0.096433	96
Sub-Total	· ·		0.263924	100	1000000	0.321446	321
Lead Frame	*	•		•			
Copper and Its Alloys	Copper	7440-50-8	24.25509	97.41	974100	29.541431	295414
Copper and Its Alloys	Iron	7439-89-6	0.5976	2.4	24000	0.727846	7278
Copper and Its Alloys	Phosphorus	7723-14-0	0.00747	0.03	300	0.009098	9:
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00747	0.03	300	0.009098	9
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00747	0.03	300	0.009098	9:
Zinc and Its Alloys	Zinc	7440-66-6	0.0249	0.1	1000	0.030327	303
Sub-Total			24.9	100	1000000	30.326898	303269
Lead Frame Plating				•			
Nickel and Its Alloys	Nickel	7440-02-0	0.355273	95.119946	951199	0.432704	432
Precious Metals	Gold	7440-57-5	0.002913	0.77992	7799	0.003548	3!
Precious Metals	Palladium	7440-05-3	0.015314	4.100134	41001	0.018652	187
Sub-Total			0.3735	100	1000000	0.454903	4549
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	42.099473	75.999999	760000	51.274956	512750
Other Organic Materials	Proprietary Non Halide Flame Retardant	Trade Secret	1.938792	3.500001	35000	2.361347	2361
Other Plastics and Rubber	Carbon Black	1333-86-4	0.166182	0.3	3000	0.202401	2024
Thermoplastics	Ероху	85954-11-6	11.189597	20.2	202000	13.628344	13628
Sub-Total			55.394044	100	1000000	67.467048	674670
Semiconductor Device				,			
Ceramics / Glass	Doped Silicon	7440-21-3	1.092898	100	1000000	1.331093	1331:
Sub-Total			1.092898	100	1000000	1.331093	1331:
Total			82.105332			100	100000

# Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

. There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs. please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
For an explanation of the methods used to determine material weights, See Product Content Methodology

## Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 databas

## Important Information/Disclaimer

Tl bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. Tl may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is." For additional information, please contact TI customer support.

# Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/08/2022

ROHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

ROHS Exempt: Means TI semiconductor products that contain lead (Pb) above the ROHS Annex II threshold, but that fall within one of the specific ROHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet 15709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.